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ABSTRACT OF THE DISCLOSURE

A process for packaging an electronic device employs an insulating protective resin layer produced from one or more of the resin compositions: (1) 100 parts of an organic solvent-soluble resin having a polysiloxane skeleton and a polar group, 0.5 to 30 parts of an epoxy compound having an epoxy equivalent of more than 800, and an organic solvent; (2) 100 parts of an organic solvent-soluble resin having a polysiloxane skeleton and a polar group, 0.1 to 10 parts of an epoxy compound having an epoxy equivalent of 100 to 800, 2 to 30 weight parts of a polyvalent isocyanate compound, and an organic solvent; and (3) 100 parts of an organic solvent-soluble resin having a polysiloxane skeleton and a polar group, 0.1 to 20 parts of an epoxy compound having an epoxy equivalent of more than 800, 2 to 30 parts of a polyvalent isocyanate compound, and an organic solvent.